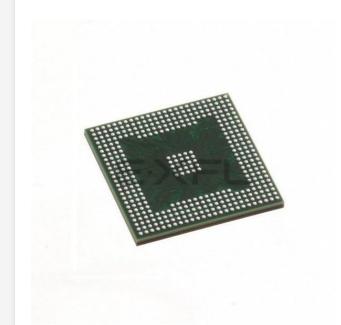
E·XFL

Intel - 5CGXFC5C6M13I7N Datasheet



Welcome to E-XFL.COM

Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Det	ails

Details	
Product Status	Active
Number of LABs/CLBs	29080
Number of Logic Elements/Cells	77000
Total RAM Bits	5001216
Number of I/O	175
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	383-TFBGA
Supplier Device Package	383-MBGA (13x13)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cgxfc5c6m13i7n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Cyclone V Device Overview	3
Key Advantages of Cyclone V Devices	3
Summary of Cyclone V Features	4
Cyclone V Device Variants and Packages	5
Cyclone V E	5
Cyclone V GX	7
Cyclone V GT	
Cyclone V SE12	2
Cyclone V SX14	4
Cyclone V ST1	5
I/O Vertical Migration for Cyclone V Devices18	3
Adaptive Logic Module	3
Variable-Precision DSP Block19	
Embedded Memory Blocks2	1
Types of Embedded Memory2	1
Embedded Memory Capacity in Cyclone V Devices	1
Embedded Memory Configurations22	2
Clock Networks and PLL Clock Sources22	2
FPGA General Purpose I/O2	3
PCIe Gen1 and Gen2 Hard IP 24	4
External Memory Interface 24	
Hard and Soft Memory Controllers24	
External Memory Performance2	
HPS External Memory Performance2	
Low-Power Serial Transceivers2	
Transceiver Channels2	
PMA Features	5
PCS Features22	
SoC with HPS28	
HPS Features28	
FPGA Configuration and Processor Booting	
Hardware and Software Development	
Dynamic and Partial Reconfiguration	
Dynamic Reconfiguration3	
Partial Reconfiguration	
Enhanced Configuration and Configuration via Protocol32	
Power Management	
Document Revision History for Cyclone V Device Overview	3



Summary of Cyclone V Features

Table 2. Summary of Features for Cyclone V Devices

Feature	Description							
Technology	TSMC's 28-nm low-p1.1 V core voltage	ower (28LP) process technology						
Packaging	 Multiple device densi different device dens 	Wirebond low-halogen packages Multiple device densities with compatible package footprints for seamless migration between different device densities RoHS-compliant and leaded ⁽¹⁾ options						
High-performance FPGA fabric	Enhanced 8-input ALM w	Enhanced 8-input ALM with four registers						
Internal memory blocks		b) memory blocks with soft error correction code (ECC) block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% memory						
Embedded Hard IP blocks	Variable-precision DSP	 Native support for up to three signal processing precision levels (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the same variable-precision DSP block 64-bit accumulator and cascade Embedded internal coefficient memory Preadder/subtractor for improved efficiency 						
	Memory controller	DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support						
	Embedded transceiver I/OPCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port							
Clock networks	, , , ,	l clock network d peripheral clock networks are not used can be powered down to reduce dynamic power						
Phase-locked loops (PLLs)	 Precision clock synth Integer mode and fra	esis, clock delay compensation, and zero delay buffering (ZDB) actional mode						
FPGA General-purpose I/Os (GPIOs)	400 MHz/800 Mbps eOn-chip termination	cond (Mbps) LVDS receiver and 840 Mbps LVDS transmitter external memory interface (OCT) p to 16 mA drive strength						
Low-power high-speed serial interface	Transmit pre-emphase	Transmit pre-emphasis and receiver equalization						
HPS (Cyclone V SE, SX, and ST devices only)	(Cyclone V SE, SX, support for symmetric and asymmetric multiprocessing							
	 System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers 							
	On-chip RAM and boo	continued						

⁽¹⁾ Contact Intel for availability.



Feature	Description
	 HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller Arm CoreSight[™] JTAG debug access port, trace port, and on-chip trace storage
Configuration	 Tamper protection—comprehensive design protection to protect your valuable IP investments Enhanced advanced encryption standard (AES) design security features CvP Dynamic reconfiguration of the FPGA Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options Internal scrubbing ⁽²⁾ Partial reconfiguration ⁽³⁾

Cyclone V Device Variants and Packages

Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

⁽²⁾ The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

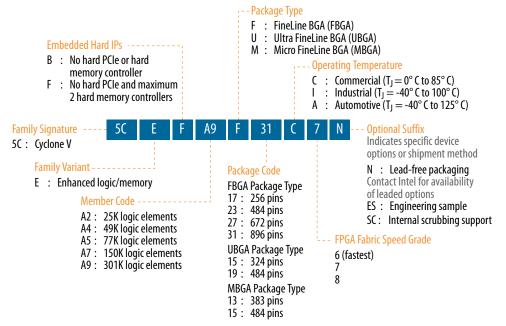
⁽³⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel[®] sales representatives.



Available Options

Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Maximum Resources

Table 4. Maximum Resource Counts for Cyclone V E Devices

Resource			Member Code						
		A2	A4	A5	A7	A9			
Logic Elements	(LE) (K)	25	49	77	150	301			
ALM		9,430	18,480	29,080	56,480	113,560			
Register		37,736	73,920	116,320	225,920	454,240			
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200			
	MLAB	196	303	424	836	1,717			
Variable-precisi	on DSP Block	25	66	150	156	342			
18 x 18 Multipli	er	50	132	300	312	684			
PLL		4	4	6	7	8			
GPIO		224	224	240	480	480			
LVDS	Transmitter	56	56	60	120	120			
	Receiver	56	56	60	120	120			
Hard Memory C	ontroller	1	1	2	2	2			



Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

Package Plan

Table 5. Package Plan for Cyclone V E Devices

Member Code	M383 (13 mm)	M484 (15 mm)	U324 (15 mm)	F256 (17 mm)	U484 (19 mm)	F484 (23 mm)	F672 (27 mm)	F896 (31 mm)
	GPIO							
A2	223	-	176	128	224	224	-	_
A4	223	-	176	128	224	224	-	_
A5	175	-	_	_	224	240	-	_
A7	-	240	_	_	240	240	336	480
A9	-	-	-	_	240	224	336	480

Cyclone V GX

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

Product Selector Guide

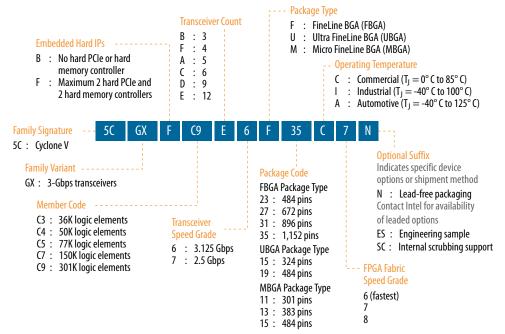
Provides the latest information about Intel products.



Available Options

Figure 2. Sample Ordering Code and Available Options for Cyclone V GX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Maximum Resources

Table 6. Maximum Resource Counts for Cyclone V GX Devices

Resource			Member Code						
		C3	C4	C5	C7	C9			
Logic Elements	(LE) (K)	36	50	77	150	301			
ALM		13,460	18,860	29,080	56,480	113,560			
Register		53,840	75,440	116,320	225,920	454,240			
Memory (Kb)	M10K	1,350	2,500	4,460	6,860	12,200			
	MLAB	182	424	424	836	1,717			
Variable-precisio	on DSP Block	57	70	150	156	342			
18 x 18 Multiplie	er	114	140	300	312	684			
PLL	PLL		6	6	7	8			
3 Gbps Transceiver		3	6	6	9	12			
GPIO ⁽⁴⁾		208	336	336	480	560			
		•	1	1	1	continued			

⁽⁴⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus[®] Prime software, the number of user I/Os includes transceiver I/Os.



Resource		Member Code						
		C3	C4	C5	C7	С9		
LVDS	Transmitter	52	84	84	120	140		
	Receiver	52	84	84	120	140		
PCIe Hard IP Block		1	2	2	2	2		
Hard Memory Controller		1	2	2	2	2		

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

Package Plan

Table 7. Package Plan for Cyclone V GX Devices

Member Code	• M301 (11 mm)		M383 (13 mm)		M484 (15 mm)		U324 (15 mm)		U484 (19 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	_	_	_	_	_	_	144	3	208	3
C4	129	4	175	6	_	-	_	-	224	6
C5	129	4	175	6	_	_	_	_	224	6
C7	—	—	—	—	240	3	—		240	6
C9	_	_	_	_	_	_	_		240	5

Member Code	F484 (23 mm)		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	208	3	_	_	_	_	_	-
C4	240	6	336	6	_	_	_	-
C5	240	6	336	6	_	_	_	-
C7	240	6	336	9	480	9	_	-
C9	224	6	336	9	480	12	560	12

Cyclone V GT

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

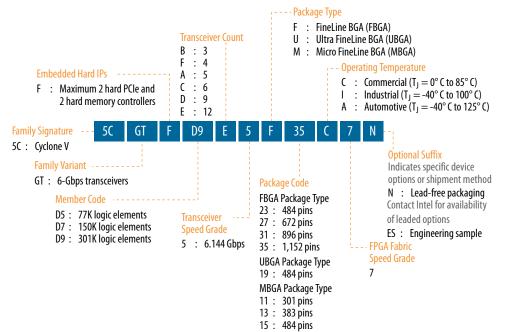
Product Selector Guide

Provides the latest information about Intel products.



Available Options

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



Maximum Resources

Table 8. Maximum Resource Counts for Cyclone V GT Devices

Resource		Member Code			
		D5	D7	D9	
Logic Elements (LE) (K)		77	150	301	
ALM		29,080	56,480	113,560	
Register		116,320	225,920	454,240	
Memory (Kb)	M10K	4,460	6,860	12,200	
	MLAB	424	836	1,717	
Variable-precision DS	P Block	150	156	342	
18 x 18 Multiplier		300	312	684	
PLL		6	7	8	
6 Gbps Transceiver		6	9	12	
GPIO ⁽⁵⁾		336	480	560	
LVDS	Transmitter	84	120	140	
				continued	

⁽⁵⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Cyclone V Device Overview CV-51001 | 2018.05.07



Resource		Member Code				
		C2	C4	C5	C6	
HPS PLL		3	3	3	3	
3 Gbps Transce	iver	6	6	9	9	
FPGA GPIO ⁽⁸⁾		145	145	288	288	
HPS I/O		181	181	181	181	
LVDS	Transmitter	32	32	72	72	
	Receiver	37	37	72	72	
PCIe Hard IP Block		2	2	2 ⁽⁹⁾	2 (9)	
FPGA Hard Memory Controller		1	1	1	1	
HPS Hard Memory Controller		1	1	1	1	
Arm Cortex-A9	MPCore Processor	Dual-core	Dual-core	Dual-core	Dual-core	

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

Package Plan

Table 13.Package Plan for Cyclone V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)				F896 (31 mm)	
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	_	-	_
C4	145	181	6	_	-	_
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

Cyclone V ST

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁹⁾ 1 PCIe Hard IP Block in U672 package.



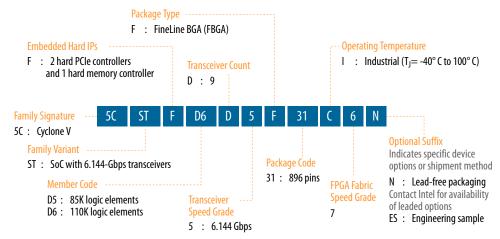
Related Information

Product Selector Guide

Provides the latest information about Intel products.

Available Options

Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices



Maximum Resources

Table 14. Maximum Resource Counts for Cyclone V ST Devices

Res	ource	Member	r Code
		D5	D6
Logic Elements (LE) (K)		85	110
ALM		32,070	41,910
Register		128,300	166,036
Memory (Kb)	M10K	3,970	5,570
	MLAB	480	621
Variable-precision DSP Block		87	112
18 x 18 Multiplier		174	224
FPGA PLL		6	6
HPS PLL		3	3
6.144 Gbps Transceiver	9		9
FPGA GPIO ⁽¹⁰⁾		288	288
HPS I/O		181	181
LVDS	Transmitter	72	72
			continued

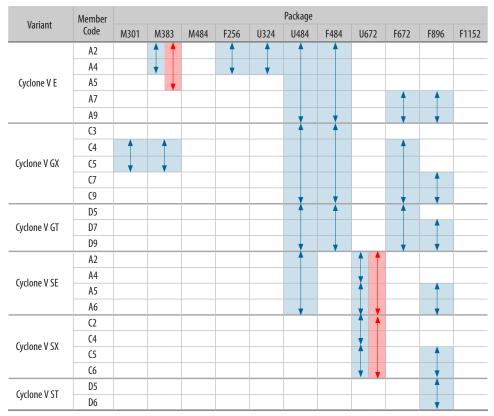
⁽¹⁰⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



I/O Vertical Migration for Cyclone V Devices

Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

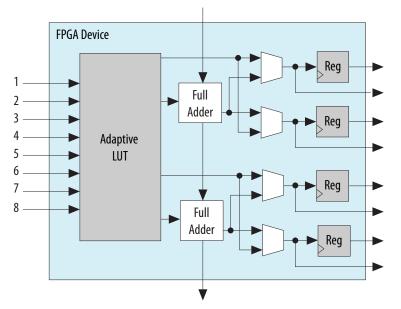
Adaptive Logic Module

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.



Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Cyclone V Devices on page 21 Lists the embedded memory capacity for each device.

Variable-Precision DSP Block

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiplyaccumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software



	Member	M10K		MLAB		Total RAM Bit
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Cyclone V GT	D5	446	4,460	679	424	4,884
	D7	686	6,860	1338	836	7,696
	D9	1,220	12,200	2748	1,717	13,917
Cyclone V SE	A2	140	1,400	221	138	1,538
	A4	270	2,700	370	231	2,460
	A5	397	3,970	768	480	4,450
	A6	553	5,530	994	621	6,151
Cyclone V SX	C2	140	1,400	221	138	1,538
	C4	270	2,700	370	231	2,460
	C5	397	3,970	768	480	4,450
	C6	553	5,530	994	621	6,151
Cyclone V ST	D5	397	3,970	768	480	4,450
	D6	553	5,530	994	621	6,151

Embedded Memory Configurations

Table 19. Supported Embedded Memory Block Configurations for Cyclone V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
M10K	256	x40 or x32
	512	x20 or x16
	1К	x10 or x8
	2К	x5 or x4
	4К	x2
	8К	×1

Clock Networks and PLL Clock Sources

550 MHz Cyclone V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Intel's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note: To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.



PLL Features

The PLLs in the Cyclone V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Dynamic phase shift
- Direct, source synchronous, zero delay buffer, external feedback, and LVDS compensation modes

Fractional PLL

In addition to integer PLLs, the Cyclone V devices use a fractional PLL architecture. The devices have up to eight PLLs, each with nine output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

Cyclone V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- LVDS output buffer with programmable differential output voltage (V_{\text{OD}}) and programmable pre-emphasis
- On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture



PCIe Gen1 and Gen2 Hard IP

Cyclone V GX, GT, SX, and ST devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen2 and Gen1 end point and root port for up to x4 lane configuration. The PCIe Gen2 x4 support is PCIe-compatible.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 9. PCIe Multifunction for Cyclone V Devices



The Cyclone V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Cyclone V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Cyclone V device provides improved end-to-end datapath protection using ECC.

External Memory Interface

This section provides an overview of the external memory interface in Cyclone V devices.

Hard and Soft Memory Controllers

Cyclone V devices support up to two hard memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Cyclone V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Cyclone V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices for maximum flexibility.



External Memory Performance

Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage	ge Maximum Frequency (MHz)		Minimum Frequency
	(V)	Hard Controller	Soft Controller	(MHz)
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Cyclone V devices deliver the industry's lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.



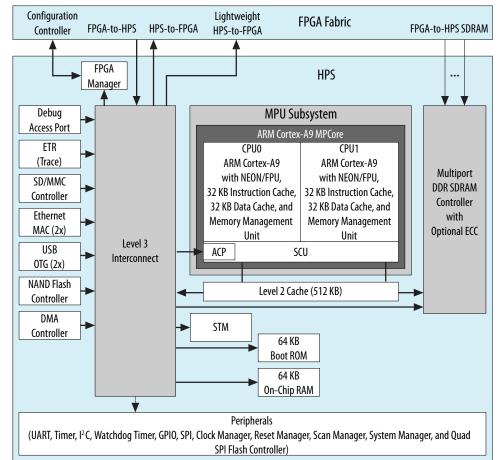


Figure 11. HPS with Dual-Core Arm Cortex-A9 MPCore Processor

System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports Arm CoreSight debug and core traces to facilitate software development.



HPS-FPGA AXI Bridges

The HPS–FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA[®]) Advanced eXtensible Interface (AXI[™]) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS–FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon[®] Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 400 MHz (800 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
 partially reconfigure the FPGA fabric at any time under software control. The HPS
 can also configure other FPGAs on the board through the FPGA configuration
 controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Cyclone V Device Overview CV-51001 | 2018.05.07



Date	Version	Changes
		 Updated MLAB RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C3: Updated from 181 to 182 Cyclone V GX C4: Updated from 295 to 424 Updated Total RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C3: Updated from 1,531 to 1,532 Cyclone V GX C4: Updated from 2,795 to 2,924 Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C4: Updated from 2,795 to 2,924 Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C4: Updated from 472 to 678 Cyclone V GX C5: Updated from 679 to 678
March 2015	2015.03.31	 Added internal scrubbing feature under configuration in Summary of Features for Cyclone V Devices table. Added optional suffix "SC: Internal scrubbing support" to the following diagrams: Sample Ordering Code and Available Options for Cyclone V E Devices Sample Ordering Code and Available Options for Cyclone V GX Devices Sample Ordering Code and Available Options for Cyclone V SE Devices Sample Ordering Code and Available Options for Cyclone V SE Devices
January 2015	2015.01.23	 Updated Sample Ordering Code and Available Options for Cyclone V ST Devices figure because Cyclone V ST devices are only available in I temperature grade and -7 speed grade. Operating Temperature: Removed C and A temperature grades FPGA Fabric Speed Grade: Removed -6 and -8 speed grades Updated the transceiver specification for Cyclone V ST from 5 Gbps to 6.144 Gbps: Device Variants for the Cyclone V Device Family table Sample Ordering Code and Available Options for Cyclone V ST Devices figure Maximum Resource Counts for Cyclone V ST Devices Updated Maximum Resource Counts for Cyclone V GX Devices table for Cyclone V GX G3 devices. Logic elements (LE) (K): Updated from 35.7 to 35.5 Variable-precision DSP block: Updated from 51 to 57 18 x 18 multiplier: Updated from 102 to 114 Updated Number of Multipliers in Cyclone V Devices table for Cyclone V GX G3 devices. Variableprecision DSP Block: Updated from 51 to 57 9 x 9 Multiplier: Updated from 102 to 114 Updated Number of Multipliers in Cyclone V Devices table for Cyclone V GX G3 devices. Variableprecision DSP Block: Updated from 51 to 57 9 x 9 Multiplier: Updated from 102 to 114 Updated Rumory Capacity and Distribution in Cyclone V Devices table for Cyclone V GX G3 devices. Multiplier Adder Mode: Updated from 51 to 57 18 x 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 18 x 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 M10K RAM bit (Kb): Updated from 1,190 to 1,350 M10K RAM bit (Kb): Updated from 1,190 to 1,350 MLAB Block: Upda
October 2014	2014.10.06	Added a footnote to the "Transceiver PCS Features for Cyclone V Devices"
		table to show that PCIe Gen2 is supported for Cyclone V GT and ST devices. continued



Date	Version	Changes
		Updated HPS I/O for U484 (19 mm) in Table 11 with '151' for A2, A4, A5 and A6.
		Updated Memory (Kb) for Maximum Resource Counts for Cyclone V SE A4 and A6, SX C4 and C6, ST D6 devices.
		Updated FPGA PLL for Maximum Resource Counts for Cyclone V SE A2, SX C2, devices.
		Removed '36 x 36' from the Variable-Precision DSP Block.
		Updated Variable-precision DSP Blocks and 18 x 18 Multiplier for Maximum Resource Counts for Cyclone V SX C4 device.
		Updated the HPS I/O counts for Cyclone V SE, SX, and ST devices.
		• Updated Figure 7 which shows the I/O vertical migration table.
		Updated Table 17 for Cyclone V SX C4 device.
		Updated Embedded Memory Capacity and Distribution table for Cyclone V SE A4 and A6, SX C4 and C6, ST D6 devices.
		Removed 'Counter reconfiguration' from the PLL Features.
		 Updated Low-Power Serial Transceivers by replacing 5 Gbps with 6.144 Gbps.
		Removed 'Distributed Memory' symbol.
		• Updated the Capability in Table 22 of Backplane support to '6.144 Gbps'.
		 Updated Capability in Table 22 of Ring oscillator transmit PLLs with 6.144 Gbps.
		Updated the PCS Support in Table 23 from 5 Gbps to '6 Gbps'.
		• Updated the Data Rates (Gbps) in Table 23 of 3 Gbps and 6 Gbps Basic to '6.144 Gbps'.
		 Updated the Data Rates (Gbps) in Table 23 of CPRI 4.1 to '6.144 Gbps'. Clarified that partial reconfiguration is an advanced feature. Contact Altera for support of the feature.
December 2012	2012.12.28	Updated the pin counts for the MBGA packages.
		Updated the GPIO and transceiver counts for the MBGA packages.
		• Updated the GPIO counts for the U484 package of the Cyclone V E A9, GX C9, and GT D9 devices.
		 Updated the vertical migration table for vertical migration of the U484 packages.
		Updated the MLAB supported programmable widths at 32 bits depth.
November 2012	2012.11.19	 Added new MBGA packages and additional U484 packages for Cyclone V E, GX, and GT.
		• Added ordering code for five-transceiver devices for Cyclone V GT and ST.
		Updated the vertical migration table to add MBGA packages.
		Added performance information for HPS memory controller.
		Removed DDR3U support.
		Updated Cyclone V ST speed grade information.
		 Added information on maximum transceiver channel usage restrictions for PCI Gen2 and CPRI at 4.9152 Gbps transmit jitter compliance.
		• Added note on the differences between GPIO reported in Overview with User I/O numbers shown in the Quartus II software.
		Updated template.
July 2012	2.1	Added support for PCIe Gen2 x4 lane configuration (PCIe-compatible)
June 2012	2.0	Restructured the document. Added the "Embedded Memory Conscitut" and "Embedded Memory
		 Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections.
		 Added Table 1, Table 3, Table 16, Table 19, and Table 20. Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 12, Table 12, Table 14, Table 17, and Table 18, Table 19, Table
		10, Table 11, Table 12, Table 13, Table 14, Table 17, and Table 18.